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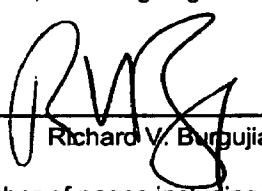


U.S. Department of Commerce
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Attorney Docket No. 06720.0166

To the Director of the U.S. Patent and Trade
Please record the attached original document.

103443325

Patent Assignment Recordation Service

1. Name of conveying party(ies): Shao-Hsin HSU Chih-Ping SUN Zhi-Hua SUN Jia-Bin YIAN		2. Name and address of receiving party(ies): Name: Industrial Technology Research Institute	
Additional name(s) of conveying party(ies) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		Internal Address:	
3. Nature of conveyance:		Street Address: Room 103, Bldg. 51, 195 Chung Hsing Rd., Sec. 4 Chutung Hsinchu, Taiwan 310 R.O.C.	
<input checked="" type="checkbox"/> Assignment	<input type="checkbox"/> Merger	City:	
<input type="checkbox"/> Security Agreement	<input type="checkbox"/> Change of Name	State:	Zip Code:
<input type="checkbox"/> Joint Research Agreement	<input type="checkbox"/> Government Interest Assignment	Additional name(s) & Address(es) attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
<input type="checkbox"/> Executive Order 9494, Confirmatory License	<input type="checkbox"/> Other:		
Execution Date: August 29, 2007			
4. Application number(s) or patent number(s): If this document is being filed together with a new application, the execution date the application: August 29, 2007			
A. Patent Application Number(s):		B. Patent Number(s):	
Additional numbers attached?		<input type="checkbox"/> Yes <input checked="" type="checkbox"/> No	
5. Name and address of party to whom correspondence concerning document should be mailed:		6. Total number of applications and patents involved 1	
Name: Richard V. Burgujian (202) 408-4000		7. Total fee (37 CFR 1.21(h) and 3.41): \$40	
Internal Address: FINNEGAN, HENDERSON, FARABOW, GARRETT & DUNNER, L.L.P.		<input checked="" type="checkbox"/> Enclosed (Please charge deficiency or credit overpayment to deposit account 06-0916)	
Street Address: 901 New York Avenue, N.W.		<input type="checkbox"/> Authorized to be charged to deposit account	
City: Washington, D.C.			
State: Zip: 20001-4413		8. Deposit Account No.: 06-0916	
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the origin document.			
Signed: 		August 30, 2007 08/31/2007 CHNGUYEN2 00000029 11896209 05 FC:8021 Date 46.00 0P	
Total number of pages including cover sheet, attachments and documents: 2			

6/2007

PATENT
REEL: 019814 FRAME: 0661

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

SYSTEMS AND METHODS FOR GENERATING AN ENTITY DIAGRAM

for which I/We executed an application for United States Letters Patent concurrently herewith or filed an application for United States Letters Patent on _____, 2007 (Application No. _____); and

WHEREAS, Industrial Technology Research Institute, a corporation of R.O.C. whose post office address is Room 103, Bldg. 51, 195, Chung Hsing Road., Sec. 4 Chutung, Hsinchu, Taiwan 310 R.O.C., (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, I/We, as Assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, my/our entire right, title, and interest in and to this invention, provisional Application No. _____, filed _____, and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of the above provisional applications, as well as all rights to claim priority on the basis of this application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I/We hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY covenant that I/We have the full right to convey the interest assigned by this Assignment, and I/We have not executed and will not execute any agreement in conflict with this Assignment;

AND, I/WE HEREBY further covenant and agree that I/We will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to me/us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I/We have hereunto set our hands

<u>HSU, SHAO-HSIN</u>	<u>Hsu Shao Hsin</u>	<u>2007 08 29</u>
FULL NAME OF FIRST INVENTOR	INVENTOR'S SIGNATURE	DATE
<u>SUN, CHIH-PING</u>	<u>Sun Chih Ping</u>	<u>2007 08 29</u>
FULL NAME OF SECOND INVENTOR	INVENTOR'S SIGNATURE	DATE
<u>SUN, ZHI-HUA</u>	<u>Sun Zhi Hua</u>	<u>2007 08 29</u>
FULL NAME OF THIRD INVENTOR	INVENTOR'S SIGNATURE	DATE
<u>YIAN, JIA-BIN</u>	<u>Yian Jia Bin</u>	<u>2007 08 29</u>
FULL NAME OF FOURTH INVENTOR	INVENTOR'S SIGNATURE	DATE